

Calmark offers the Series 165 and 166 Card Retainer as the answer to the PC card heat sinking and grounding problems. The series 165 and 166 provides an excellent thermal path from the card to the chassis. Alloy 10 beryllium copper furnishes exceptionally high thermal conductivity (1600 BTU/sq. ft/hr in./°F) and electrical conductivity (48-55% IACS). Conforms to DESC 85034.

### FEATURES:

**Mounting holes are offset from card path and occur every inch, offering a choice of mounting patterns and maximum contact with chassis.**

**Coined edges allow smooth insertion and extraction without damage to card.**

**Independent sections maximize contact with card.**

**Turned in tabs and rigid wall limit card excursion under dynamic loading.**

**Spring fingers hold card against rigid side for thermal and electrical contact. Also provides dampening under shock and vibration.**



**Series 165 - Shown**  
**Series 166 - Opposite**

**MATERIAL:** .016 (0.41) Alloy 10 Beryllium Copper. Cond. "AT" per MIL-C-81021

**FINISH:** No Finish

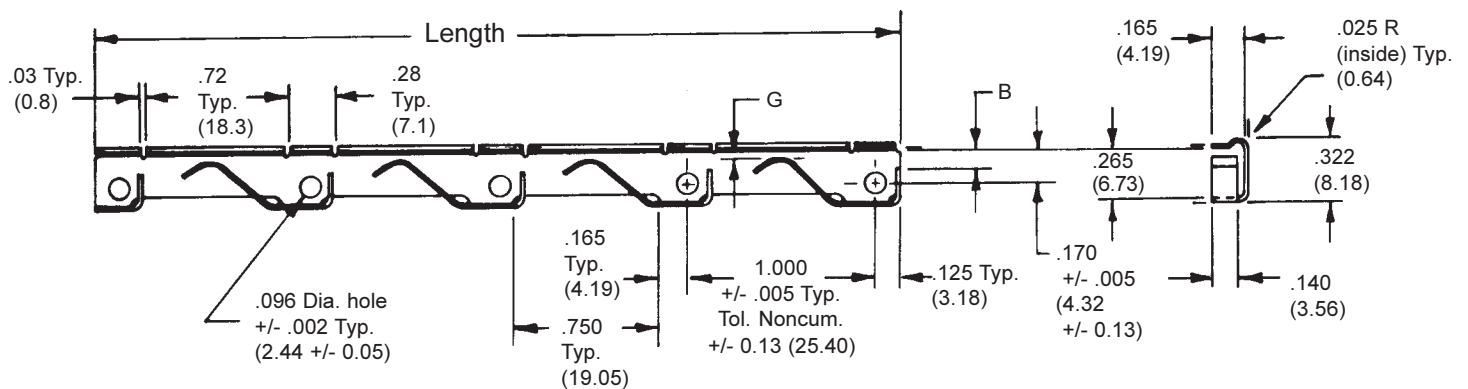
**WEIGHT:** .043 oz./inch (.48g/cm)

**SPRING RATE:** 32 lbs./inch of deflection/spring finger (56.0 N/cm)

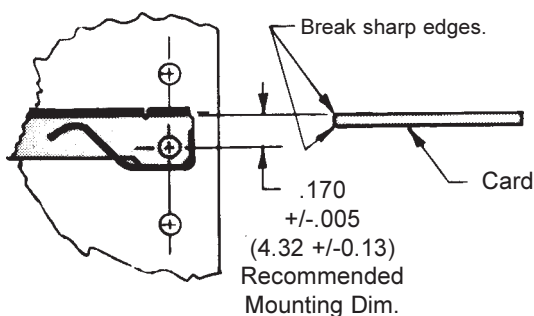
**TOLERANCES:** .xxx = +/- .010, .xx = +/- .02  
(.xx = +/- 0.25, .xx = +/- 0.5)

### TABULATION

Dash No.	Card Thickness	B Dim. +.015 (+0.38) -.000 (-0.0)	G Dim +.00 (0.0) -.03 (-0.80)
-06	1/16 (1.6)	.075 (1.91)	.045 (1.14)
-09	3/32 (2.4)	.105 (2.67)	.075 (1.91)



### APPLICATION DATA:



### PART NO. CODE

165-06-3.25

Length (1.25 thru 12.25 by 1" increments)  
Longer lengths available on request.

Card thickness (see Tabulation)

165-Shown  
166-Opposite